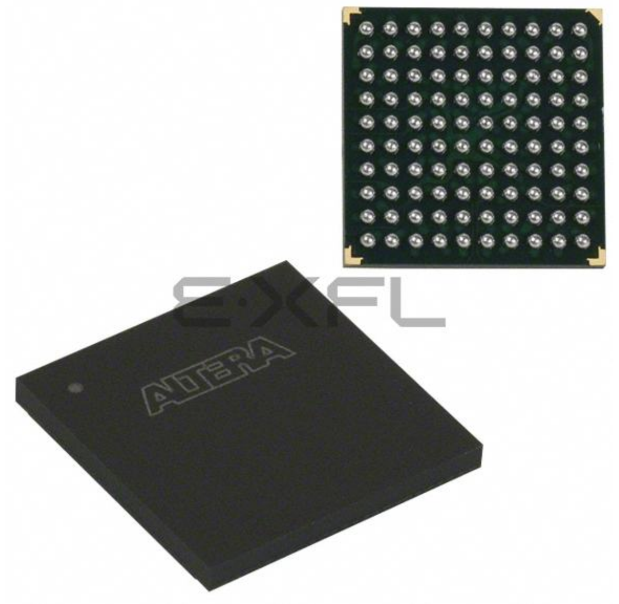

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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	2.375V ~ 2.625V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	84
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LBGA
Supplier Device Package	100-FBGA (11x11)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7128bfc100-7

MAX 7000B devices provide programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate up to 50% lower power while adding only a nominal timing delay. MAX 7000B devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000B devices can be set for 3.3 V, 2.5 V, or 1.8 V and all input pins are 3.3-V, 2.5-V, and 1.8-V tolerant, allowing MAX 7000B devices to be used in mixed-voltage systems.

MAX 7000B devices are supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. Altera software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. Altera software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.

For more information on development tools, see the *MAX+PLUS II Programmable Logic Development System & Software Data Sheet* and the *Quartus Programmable Logic Development System & Software Data Sheet*.

Functional Description

The MAX 7000B architecture includes the following elements:

- LABs
- Macrocells
- Expander product terms (shareable and parallel)
- PIA
- I/O control blocks

The MAX 7000B architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of MAX 7000B devices.

Expander Product Terms

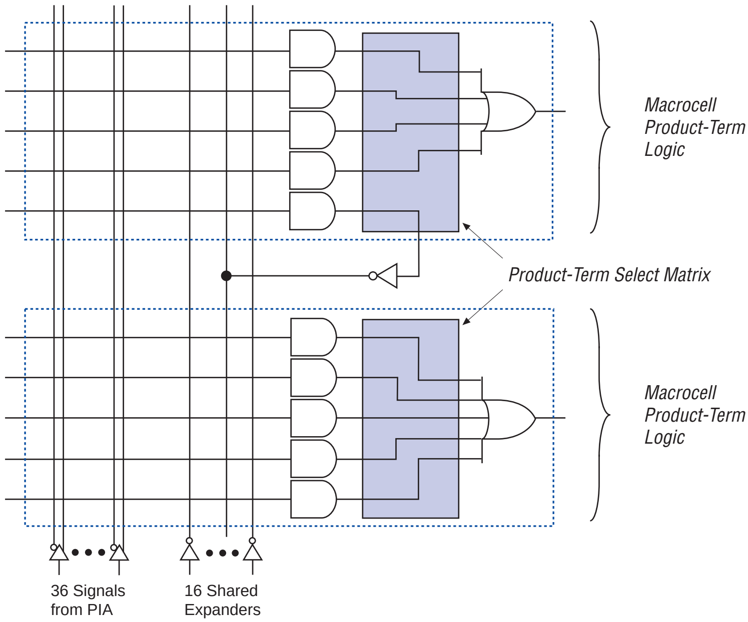
Although most logic functions can be implemented with the five product terms available in each macrocell, more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources. However, the MAX 7000B architecture also offers both shareable and parallel expander product terms ("expanders") that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

Shareable Expanders

Each LAB has 16 shareable expanders that can be viewed as a pool of uncommitted single product terms (one from each macrocell) with inverted outputs that feed back into the logic array. Each shareable expander can be used and shared by any or all macrocells in the LAB to build complex logic functions. A small delay (t_{SEXP}) is incurred when shareable expanders are used. Figure 3 shows how shareable expanders can feed multiple macrocells.

Figure 3. MAX 7000B Shareable Expanders

Shareable expanders can be shared by any or all macrocells in an LAB.



In-System Programmability (ISP)

MAX 7000B devices can be programmed in-system via an industry-standard 4-pin IEEE Std. 1149.1 (JTAG) interface. ISP offers quick, efficient iterations during design development and debugging cycles. The MAX 7000B architecture internally generates the high programming voltages required to program EEPROM cells, allowing in-system programming with only a single 2.5-V power supply. During in-system programming, the I/O pins are tri-stated and weakly pulled-up to eliminate board conflicts. The pull-up value is nominally 50 k¾.

MAX 7000B devices have an enhanced ISP algorithm for faster programming. These devices also offer an ISP_Done bit that provides safe operation when in-system programming is interrupted. This ISP_Done bit, which is the last bit programmed, prevents all I/O pins from driving until the bit is programmed.

ISP simplifies the manufacturing flow by allowing devices to be mounted on a PCB with standard pick-and-place equipment before they are programmed. MAX 7000B devices can be programmed by downloading the information via in-circuit testers, embedded processors, the Altera MasterBlaster communications cable, and the ByteBlasterMV parallel port download cable. Programming the devices after they are placed on the board eliminates lead damage on high-pin-count packages (e.g., QFP packages) due to device handling. MAX 7000B devices can be reprogrammed after a system has already shipped to the field. For example, product upgrades can be performed in the field via software or modem.

In-system programming can be accomplished with either an adaptive or constant algorithm. An adaptive algorithm reads information from the unit and adapts subsequent programming steps to achieve the fastest possible programming time for that unit. A constant algorithm uses a pre-defined (non-adaptive) programming sequence that does not take advantage of adaptive algorithm programming time improvements. Some in-circuit testers cannot program using an adaptive algorithm. Therefore, a constant algorithm must be used. MAX 7000B devices can be programmed with either an adaptive or constant (non-adaptive) algorithm.

The Jam Standard Test and Programming Language (STAPL), JEDEC standard JESD-71, can be used to program MAX 7000B devices with in-circuit testers, PCs, or embedded processors.

For more information on using the Jam language, see *Application Note 88 (Using the Jam Language for ISP & ICR via an Embedded Processor)* and *Application Note 122 (Using STAPL for ISP & ICR via an Embedded Processor)*.

The ISP circuitry in MAX 7000B devices is compliant with the IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000B Device

The time required to program a single MAX 7000B device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where: t_{PROG} = Programming time
t_{PPULSE} = Sum of the fixed times to erase, program, and verify the EEPROM cells
$Cycle_{PTCK}$ = Number of TCK cycles to program a device
f_{TCK} = TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000B device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where: t_{VER} = Verify time
t_{VPULSE} = Sum of the fixed times to verify the EEPROM cells
$Cycle_{VTCK}$ = Number of TCK cycles to verify a device

Programming with External Hardware

MAX 7000B devices can be programmed on Windows-based PCs with an Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs continuity checking to ensure adequate electrical contact between the adapter and the device.

For more information, see the *Altera Programming Hardware Data Sheet*.

The Altera software can use text- or waveform-format test vectors created with the Altera Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional device behavior with the results of simulation.

Data I/O, BP Microsystems, and other programming hardware manufacturers provide programming support for Altera devices. For more information, see *Programming Hardware Manufacturers*.

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

MAX 7000B devices include the JTAG boundary-scan test circuitry defined by IEEE Std. 1149.1. Table 6 describes the JTAG instructions supported by MAX 7000B devices. The pin-out tables starting on page 59 of this data sheet show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

Table 6. MAX 7000B JTAG Instructions

JTAG Instruction	Description
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	Places the 1-bit bypass register between the `TDI` and `TDO` pins, which allows the boundary-scan test data to pass synchronously through a selected device to adjacent devices during normal operation.
CLAMP	Allows the values in the boundary-scan register to determine pin states while placing the 1-bit bypass register between the `TDI` and `TDO` pins.
IDCODE	Selects the IDCODE register and places it between the `TDI` and `TDO` pins, allowing the IDCODE to be serially shifted out of `TDO`.
USERCODE	Selects the 32-bit USERCODE register and places it between the `TDI` and `TDO` pins, allowing the USERCODE value to be shifted out of `TDO`.
ISP Instructions	These instructions are used when programming MAX 7000B devices via the JTAG ports with the MasterBlaster or ByteBlasterMV download cable, or using a Jam File (**.jam**), Jam Byte-Code File (**.jbc**), or Serial Vector Format File (**.svf**) via an embedded processor or test equipment.

Programmable Speed/Power Control

MAX 7000B devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000B device for either high-speed or low-power operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder (t_{LPA}) for the t_{LAD}, t_{LAC}, t_{IC}, t_{ACL}, t_{CPPW}, t_{EN}, and t_{SEXP} parameters.

Output Configuration

MAX 7000B device outputs can be programmed to meet a variety of system-level requirements.

MultiVolt I/O Interface

The MAX 7000B device architecture supports the MultiVolt I/O interface feature, which allows MAX 7000B devices to connect to systems with differing supply voltages. MAX 7000B devices in all packages can be set for 3.3-V, 2.5-V, or 1.8-V pin operation. These devices have one set of V_{CC} pins for internal operation and input buffers (`VCCINT`), and another set for I/O output drivers (`VCCIO`).

The `VCCIO` pins can be connected to either a 3.3-V, 2.5-V, or 1.8-V power supply, depending on the output requirements. When the `VCCIO` pins are connected to a 1.8-V power supply, the output levels are compatible with 1.8-V systems. When the `VCCIO` pins are connected to a 2.5-V power supply, the output levels are compatible with 2.5-V systems. When the `VCCIO` pins are connected to a 3.3-V power supply, the output high is at 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V_{CCIO} levels of 2.5 V or 1.8 V incur a nominal timing delay adder.

Table 10 describes the MAX 7000B MultiVolt I/O support.

Table 10. MAX 7000B MultiVolt I/O Support

V_{CCIO} (V)	Input Signal (V)				Output Signal (V)			
	1.8	2.5	3.3	5.0	1.8	2.5	3.3	5.0
1.8	✓	✓	✓		✓			
2.5	✓	✓	✓			✓		
3.3	✓	✓	✓				✓	✓

Open-Drain Output Option

MAX 7000B devices provide an optional open-drain (equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

Programmable Ground Pins

Each unused I/O pin on MAX 7000B devices may be used as an additional ground pin. This programmable ground feature does not require the use of the associated macrocell; therefore, the buried macrocell is still available for user logic.

Slew-Rate Control

The output buffer for each MAX 7000B I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. When the configuration cell is turned off, the slew rate is set for low-noise performance. Each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis. The slew rate control affects both the rising and falling edges of the output signal.

Advanced I/O Standard Support

The MAX 7000B I/O pins support the following I/O standards: LVTTL, LVCMOS, 1.8-V I/O, 2.5-V I/O, GTL+, SSTL-3 Class I and II, and SSTL-2 Class I and II.

MAX 7000B devices contain two I/O banks. Both banks support all standards. Each I/O bank has its own VCCIO pins. A single device can support 1.8-V, 2.5-V, and 3.3-V interfaces; each bank can support a different standard independently. Within a bank, any one of the terminated standards can be supported.

Figure 9 shows the arrangement of the MAX 7000B I/O banks.

Figure 9. MAX 7000B I/O Banks for Various Advanced I/O Standards

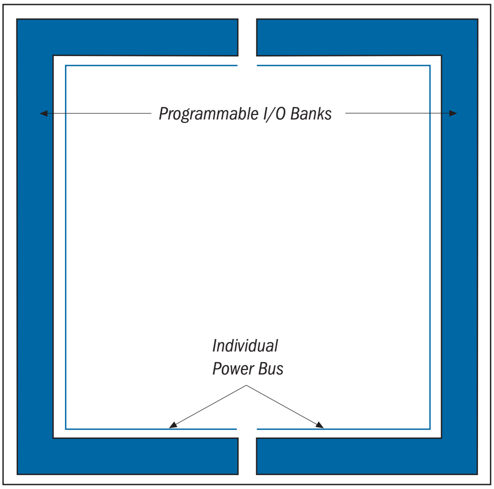


Table 11 shows which macrocells have pins in each I/O bank.

Table 11. Macrocell Pins Contained in Each I/O Bank

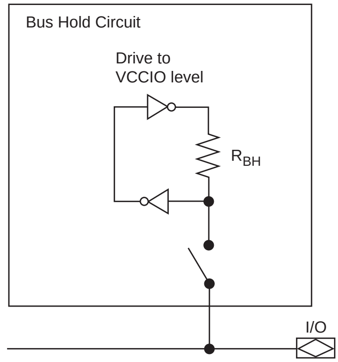
Device	Bank 1	Bank 2
EPM7032B	1-16	17-32
EPM7064B	1-32	33-64
EPM7128B	1-64	65-128
EPM7256B	1-128, 177-181	129-176, 182-256
EPM7512B	1-265	266-512

Each MAX 7000B device has two VREF pins. Each can be set to a separate V_{REF} level. Any I/O pin that uses one of the voltage-referenced standards (GTL+, SSTL-2, or SSTL-3) may use either of the two VREF pins. If these pins are not required as VREF pins, they may be individually programmed to function as user I/O pins.

Two inverters implement the bus-hold circuitry in a loop that weakly drives back to the I/O pin in user mode.

Figure 10 shows a block diagram of the bus-hold circuit.

Figure 10. Bus-Hold Circuit



PCI Compatibility

MAX 7000B devices are compatible with PCI applications as well as all 3.3-V electrical specifications in the ***PCI Local Bus Specification Revision 2.2*** except for the clamp diode. While having multiple clamp diodes on a signal trace may be redundant, designers can add an external clamp diode to meet the specification. Table 13 shows the MAX 7000B device speed grades that meet the PCI timing specifications.

Table 13. MAX 7000B Device Speed Grades that Meet PCI Timing Specifications

Device	Specification	
	33-MHz PCI	66-MHz PCI
EPM7032B	All speed grades	-3
EPM7064B	All speed grades	-3
EPM7128B	All speed grades	-4
EPM7256B	All speed grades	-5 *(1)*
EPM7512B	All speed grades	-5 *(1)*

Note:

(1) The EPM7256B and EPM7512B devices in a -5 speed grade meet all PCI timing specifications for 66-MHz operation except the Input Setup Time to CLK—Bused Signal parameter. However, these devices are within 1 ns of that parameter. EPM7256B and EPM7512B devices meet all other 66-MHz PCI timing specifications.

Power Sequencing & Hot-Socketing

Because MAX 7000B devices can be used in a mixed-voltage environment, they have been designed specifically to tolerate any possible power-up sequence. The V_{CCIO} and V_{CCINT} power planes can be powered in any order.

Signals can be driven into MAX 7000B devices before and during power-up (and power-down) without damaging the device. Additionally, MAX 7000B devices do not drive out during power-up. Once operating conditions are reached, MAX 7000B devices operate as specified by the user.

MAX 7000B device I/O pins will not source or sink more than 300 µA of DC current during power-up. All pins can be driven up to 4.1 V during hot-socketing.

Design Security

All MAX 7000B devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security, because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.

Generic Testing

MAX 7000B devices are fully functionally tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in Figure 11. Test patterns can be used and then erased during early stages of the production flow.

Table 16. MAX 7000B Device DC Operating Conditions *Note (4)*					
Symbol	**Parameter**	**Conditions**	**Min**	**Max**	**Unit**
V_{IH}	High-level input voltage for 3.3-V TTL/CMOS		2.0	3.9	V
	High-level input voltage for 2.5-V TTL/CMOS		1.7	3.9	V
	High-level input voltage for 1.8-V TTL/CMOS		$0.65 \times V_{CCIO}$	3.9	V
V_{IL}	Low-level input voltage for 3.3-V TTL/CMOS and PCI compliance		–0.5	0.8	V
	Low-level input voltage for 2.5-V TTL/CMOS		–0.5	0.7	V
	Low-level input voltage for 1.8-V TTL/CMOS		–0.5	$0.35 \times V_{CCIO}$	
V_{OH}	3.3-V high-level TTL output voltage	I_{OH} = –8 mA DC, V_{CCIO} = 3.00 V *(5)*	2.4		V
	3.3-V high-level CMOS output voltage	I_{OH} = –0.1 mA DC, V_{CCIO} = 3.00 V *(5)*	V_{CCIO} – 0.2		V
	2.5-V high-level output voltage	I_{OH} = –100 µA DC, V_{CCIO} = 2.30 V *(5)*	2.1		V
		I_{OH} = –1 mA DC, V_{CCIO} = 2.30 V *(5)*	2.0		V
		I_{OH} = –2 mA DC, V_{CCIO} = 2.30 V *(5)*	1.7		V
	1.8-V high-level output voltage	I_{OH} = –2 mA DC, V_{CCIO} =1.65 V *(5)*	1.2		V
V_{OL}	3.3-V low-level TTL output voltage	I_{OL} = 8 mA DC, V_{CCIO} = 3.00 V *(6)*		0.4	V
	3.3-V low-level CMOS output voltage	I_{OL} = 0.1 mA DC, V_{CCIO} = 3.00 V *(6)*		0.2	V
	2.5-V low-level output voltage	I_{OL} = 100 µA DC, V_{CCIO} = 2.30 V *(6)*		0.2	V
		I_{OL} = 1 mA DC, V_{CCIO} = 2.30 V *(6)*		0.4	V
		I_{OL} = 2 mA DC, V_{CCIO} = 2.30 V *(6)*		0.7	V
	1.8-V low-level output voltage	I_{OL} = 2 mA DC, V_{CCIO} = 1.7 V *(6)*		0.4	V
I_I	Input leakage current	V_I = –0.5 to 3.9 V *(7)*	–10	10	µA
I_{OZ}	Tri-state output off-state current	V_I = –0.5 to 3.9 V *(7)*	–10	10	µA
R_{ISP}	Value of I/O pin pull-up resistor during in-system programming or during power up	V_{CCIO} = 1.7 to 3.6 V *(8)*	20	74	k¾

Figure 14. MAX 7000B Switching Waveforms

t_R & t_F < 2 ns. Inputs are driven at 3.0 V for a logic high and 0 V for a logic low. All timing characteristics are measured at 1.5 V.

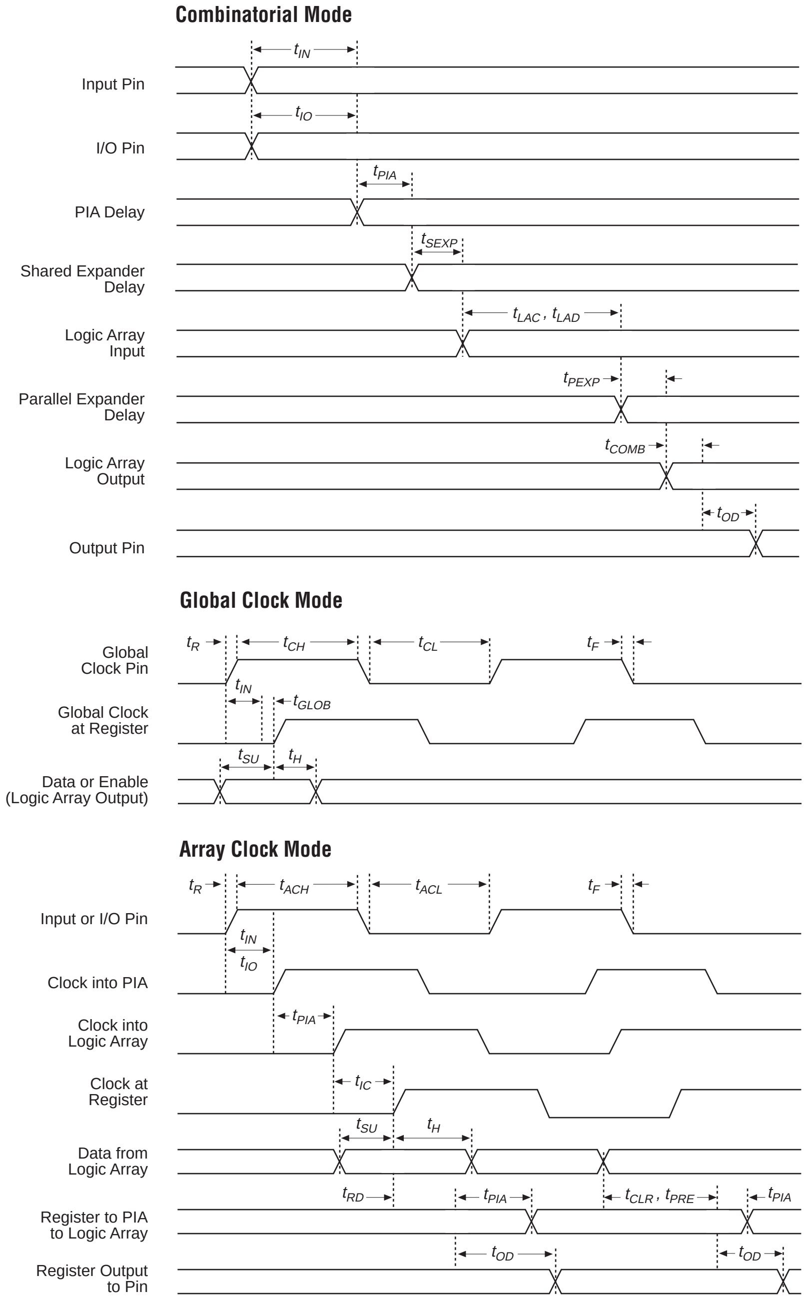


Table 20. EPM7032B Selectable I/O Standard Timing Adder Delays *Notes (1)*								
I/O Standard	Parameter	Speed Grade						Unit
		-3.5		-5.0		-7.5		
		Min	Max	Min	Max	Min	Max	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

Notes to tables:

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of all LABs.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(4) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{ACL}, t_{CPPW}, t_{EN}, and t_{SEXP} parameters for macrocells running in low-power mode.

Table 22. EPM7064B Internal Timing Parameters *Note (1)*									
Symbol	**Parameter**	**Conditions**	**Speed Grade**						**Unit**
			-3		**-5**		**-7**		
			Min	**Max**	**Min**	**Max**	**Min**	**Max**	
t_{IN}	Input pad and buffer delay			0.3		0.5		0.7	ns
t_{IO}	I/O input pad and buffer delay			0.3		0.5		0.7	ns
t_{FIN}	Fast input delay			0.9		1.3		2.0	ns
t_{FIND}	Programmable delay adder for fast input			1.0		1.5		1.5	ns
t_{SEXP}	Shared expander delay			1.5		2.1		3.2	ns
t_{PEXP}	Parallel expander delay			0.4		0.6		0.9	ns
t_{LAD}	Logic array delay			1.4		2.0		3.1	ns
t_{LAC}	Logic control array delay			1.2		1.7		2.6	ns
t_{IOE}	Internal output enable delay			0.1		0.2		0.3	ns
t_{OD1}	Output buffer and pad delay slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF		0.9		1.2		1.8	ns
t_{OD3}	Output buffer and pad delay slow slew rate = on V_{CCIO} = 2.5 V or 3.3 V	C1 = 35 pF		5.9		6.2		6.8	ns
t_{ZX1}	Output buffer enable delay slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF		1.6		2.2		3.4	ns
t_{ZX3}	Output buffer enable delay slow slew rate = on V_{CCIO} = 2.5 V or 3.3 V	C1 = 35 pF		6.6		7.2		8.4	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		1.6		2.2		3.4	ns
t_{SU}	Register setup time		0.7		1.1		1.6		ns
t_{H}	Register hold time		0.4		0.5		0.9		ns
t_{FSU}	Register setup time of fast input		0.8		0.8		1.1		ns
t_{FH}	Register hold time of fast input		1.2		1.2		1.4		ns
t_{RD}	Register delay			0.5		0.6		0.9	ns
t_{COMB}	Combinatorial delay			0.2		0.3		0.5	ns
t_{IC}	Array clock delay			1.2		1.8		2.8	ns
t_{EN}	Register enable time			1.2		1.7		2.6	ns
t_{GLOB}	Global control delay			0.7		1.1		1.6	ns
t_{PRE}	Register preset time			1.0		1.3		1.9	ns
t_{CLR}	Register clear time			1.0		1.3		1.9	ns
t_{PIA}	PIA delay	*(2)*		0.7		1.0		1.4	ns
t_{LPA}	Low-power adder	*(4)*		1.5		2.1		3.2	ns

Table 28. EPM7256B Internal Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.4		0.6		0.8	ns
t_{IO}	I/O input pad and buffer delay			0.4		0.6		0.8	ns
t_{FIN}	Fast input delay			1.5		2.5		3.1	ns
t_{FIND}	Programmable delay adder for fast input			1.5		1.5		1.5	ns
t_{SEXP}	Shared expander delay			1.5		2.3		3.0	ns
t_{PEXP}	Parallel expander delay			0.4		0.6		0.8	ns
t_{LAD}	Logic array delay			1.7		2.5		3.3	ns
t_{LAC}	Logic control array delay			1.5		2.2		2.9	ns
t_{IOE}	Internal output enable delay			0.1		0.2		0.3	ns
t_{OD1}	Output buffer and pad delay slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF		0.9		1.4		1.9	ns
t_{OD3}	Output buffer and pad delay slow slew rate = on V_{CCIO} = 2.5 V or 3.3 V	C1 = 35 pF		5.9		6.4		6.9	ns
t_{ZX1}	Output buffer enable delay slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF		2.2		3.3		4.5	ns
t_{ZX3}	Output buffer enable delay slow slew rate = on V_{CCIO} = 2.5 V or 3.3 V	C1 = 35 pF		7.2		8.3		9.5	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		2.2		3.3		4.5	ns
t_{SU}	Register setup time		1.2		1.8		2.5		ns
t_{H}	Register hold time		0.6		1.0		1.3		ns
t_{FSU}	Register setup time of fast input		0.8		1.1		1.1		ns
t_{FH}	Register hold time of fast input		1.2		1.4		1.4		ns
t_{RD}	Register delay			0.7		1.0		1.3	ns
t_{COMB}	Combinatorial delay			0.3		0.4		0.5	ns
t_{IC}	Array clock delay			1.5		2.3		3.0	ns
t_{EN}	Register enable time			1.5		2.2		2.9	ns
t_{GLOB}	Global control delay			1.3		2.1		2.7	ns
t_{PRE}	Register preset time			1.0		1.6		2.1	ns
t_{CLR}	Register clear time			1.0		1.6		2.1	ns
t_{PIA}	PIA delay	*(2)*		1.7		2.6		3.3	ns
t_{LPA}	Low-power adder	*(4)*		2.0		3.0		4.0	ns

Table 29. EPM7256B Selectable I/O Standard Timing Adder Delays (Part 2 of 2) Note (1)								
I/O Standard	**Parameter**	**Speed Grade**						**Unit**
		-5		**-7**		**-10**		
		Min	**Max**	**Min**	**Max**	**Min**	**Max**	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

Notes to tables:

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(4) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{ACL}, t_{CPPW}, t_{EN}, and t_{SEXP} parameters for macrocells running in low-power mode.

Table 31. EPM7512B Internal Timing Parameters *Note (1)*									
Symbol	**Parameter**	**Conditions**	**Speed Grade**						**Unit**
			-5		**-7**		**-10**		
			Min	**Max**	**Min**	**Max**	**Min**	**Max**	
t_{IN}	Input pad and buffer delay			0.3		0.3		0.5	ns
t_{IO}	I/O input pad and buffer delay			0.3		0.3		0.5	ns
t_{FIN}	Fast input delay			2.2		3.2		4.0	ns
t_{FIND}	Programmable delay adder for fast input			1.5		1.5		1.5	ns
t_{SEXP}	Shared expander delay			1.5		2.1		2.7	ns
t_{PEXP}	Parallel expander delay			0.4		0.5		0.7	ns
t_{LAD}	Logic array delay			1.7		2.3		3.0	ns
t_{LAC}	Logic control array delay			1.5		2.0		2.6	ns
t_{IOE}	Internal output enable delay			0.1		0.2		0.2	ns
t_{OD1}	Output buffer and pad delay slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF		0.9		1.2		1.6	ns
t_{OD3}	Output buffer and pad delay slow slew rate = on V_{CCIO} = 2.5 V or 3.3 V	C1 = 35 pF		5.9		6.2		6.6	ns
t_{ZX1}	Output buffer enable delay slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF		2.8		3.8		5.0	ns
t_{ZX3}	Output buffer enable delay slow slew rate = on V_{CCIO} = 2.5 V or 3.3 V	C1 = 35 pF		7.8		8.8		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		2.8		3.8		5.0	ns
t_{SU}	Register setup time		1.5		2.0		2.6		ns
t_{H}	Register hold time		0.4		0.5		0.7		ns
t_{FSU}	Register setup time of fast input		0.8		1.1		1.1		ns
t_{FH}	Register hold time of fast input		1.2		1.4		1.4		ns
t_{RD}	Register delay			0.5		0.7		1.0	ns
t_{COMB}	Combinatorial delay			0.2		0.3		0.4	ns
t_{IC}	Array clock delay			1.8		2.4		3.1	ns
t_{EN}	Register enable time			1.5		2.0		2.6	ns
t_{GLOB}	Global control delay			2.0		2.8		3.6	ns
t_{PRE}	Register preset time			1.0		1.4		1.9	ns
t_{CLR}	Register clear time			1.0		1.4		1.9	ns
t_{PIA}	PIA delay	*(2)*		2.4		3.4		4.5	ns
t_{LPA}	Low-power adder	*(4)*		2.0		2.7		3.6	ns

Figure 15. I_{CC} vs. Frequency for EPM7032B Devices

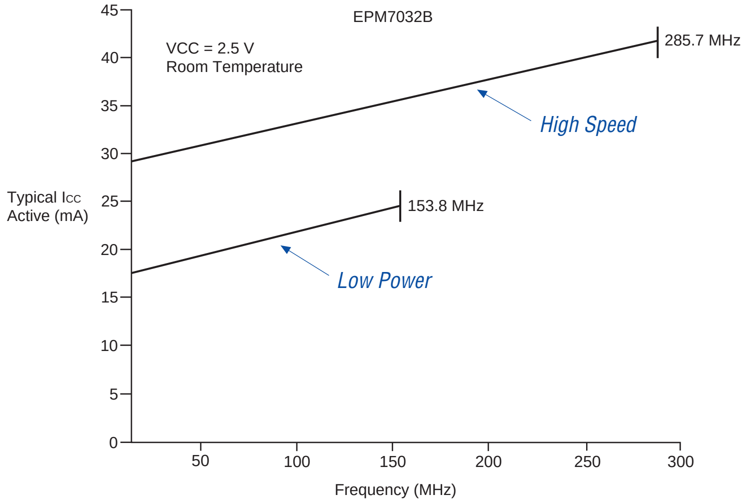


Figure 16. I_{CC} vs. Frequency for EPM7064B Devices

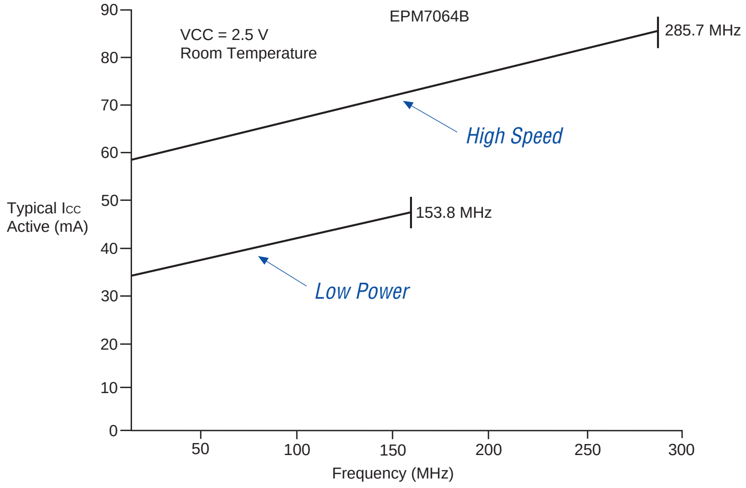


Figure 19. I_{CC} vs. Frequency for EPM7512B Devices

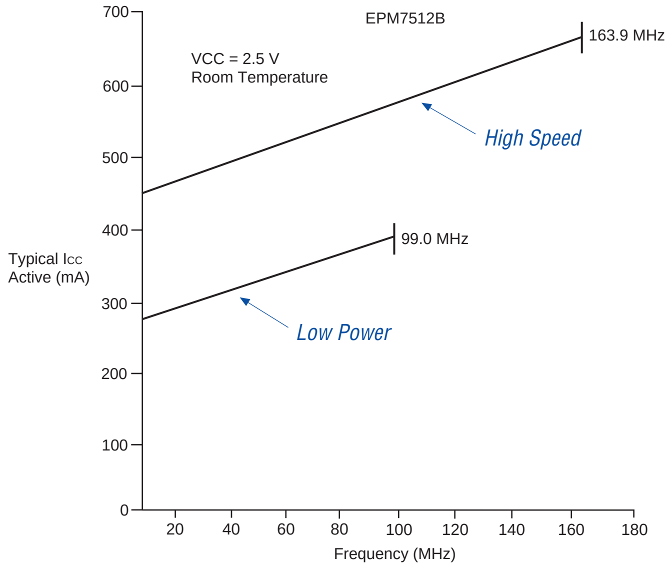


Figure 21. 48-Pin VTQFP Package Pin-Out Diagram

Package outlines not drawn to scale.

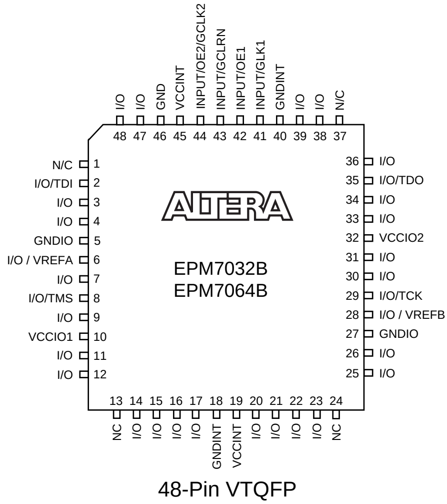


Figure 22. 49-Pin Ultra FineLine BGA Package Pin-Out Diagram

Package outline not drawn to scale.